



Material Content Data Sheet



Sales Product Name		BFP 720 H6327		Issued		24. January 2018			
MA#		MA001687192							
Package		PG-SOT343-4-2		Weight*		6.93 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.01		100		
	noble metal	gold	7440-57-5	0.003	0.04		389		
	inorganic material	silicon	7440-21-3	0.024	0.34	0.39	3421	3910	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100		
	non noble metal	titanium	7440-32-6	0.003	0.05		498		
	non noble metal	chromium	7440-47-3	0.010	0.15		1493		
	non noble metal	copper	7440-50-8	3.433	49.55	49.76	495528	497619	
wire	noble metal	gold	7440-57-5	0.010	0.14	0.14	1414	1414	
	encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4371	
		plastics	epoxy resin	-	0.651	9.40		93973	
	inorganic material	silicondioxide	60676-86-0	2.347	33.87	43.71	338742	437086	
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28756	28756	
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31215	31215	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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